

DIGITRON SEMICONDUCTORS

MCR25D, MCR25M, MCR25N

SILICON CONTROLLED RECTIFIERS

Available Non-RoHS (standard) or RoHS compliant (add PBF suffix).
Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak repetitive off-state voltage ⁽¹⁾ (T _J = -40 to +125°C, sine wave, 50 to 60Hz) MCR25D MCR25M MCR25N	V _{DRM} V _{RRM}	400 600 800	V
On-state RMS current (180° conduction angles, T _C = 80°C)	I _{T(RMS)}	25	A
Peak non-repetitive surge current (half-cycle, sine wave, 60Hz, T _J = 125°C)	I _{TSM}	300	A
Circuit fusing consideration (t = 8.3ms)	I ² t	373	A ² s
Forward peak gate power (pulse width ≤ 1.0μs, T _C = 80°C)	P _{GM}	20	W
Forward average gate power (t = 8.3ms, T _C = 80°C)	P _{G(AV)}	0.5	W
Forward peak gate current (pulse width ≤ 1.0μs, T _C = 80°C)	I _{GM}	2.0	A
Operating junction temperature range	T _J	-40 to +125	°C
Storage temperature range	T _{stg}	-40 to +150	°C

Note 1: V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Maximum	Unit
Thermal resistance, junction to case	R _{θJC}	1.5	°C/W
Thermal resistance, junction to ambient	R _{θJA}	62.5	°C/W
Lead solder temperature (lead length ≥ 1/8" from case, 10s max)	T _L	260	°C

ELECTRICAL CHARACTERISTICS (T_J = 25°C, unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS start here					
Peak forward or reverse blocking current (V _{AK} = Rated V _{DRM} or V _{RRM} , gate open) T _J = 25°C T _J = 125°C	I _{DRM} , I _{RRM}	- -	- -	0.01 2.0	mA
ON CHARACTERISTICS					
Peak forward on-state voltage * (I _{TM} = 50A)	V _{TM}	-	-	1.8	V
Gate trigger current (continuous dc) (V _D = 12V, R _L = 100Ω)	I _{GT}	4.0	12	30	mA
Gate trigger voltage (continuous dc) (V _D = 12V, R _L = 100Ω)	V _{GT}	0.5	0.67	1.0	V
Holding current (V _D = 12V, gate open, initiating current = 200mA)	I _H	5.0	13	40	mA
Latching current (V _D = 12V, I _G = 30mA)	I _L	-	35	80	mA
DYNAMIC CHARACTERISTICS					
Critical rate of rise of off-state voltage (V _D = 67% of rated V _{DRM} , exponential waveform, gate open, T _J = 125°C)	dv/dt	100	250	-	V/μs
Critical rate of rise of on-state current (I _{PK} = 50A, PW = 30μsec, di _c /dt = 1A/μsec, I _{gt} = 50mA)	di/dt	-	-	50	A/μs

* Pulse width ≤ 2.0ms, duty cycle ≤ 2%.

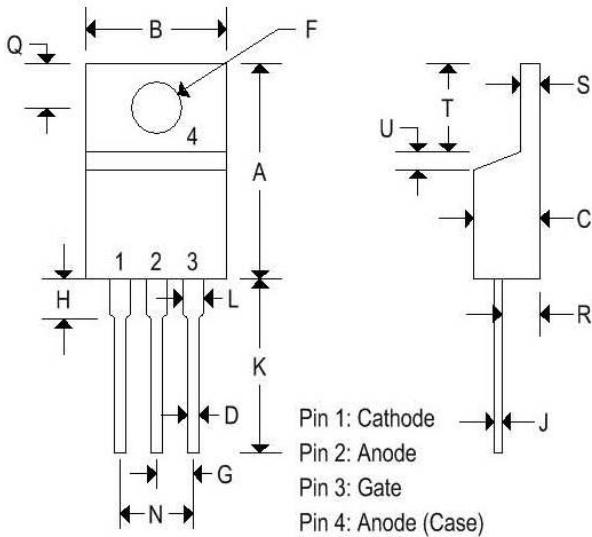
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MECHANICAL CHARACTERISTICS

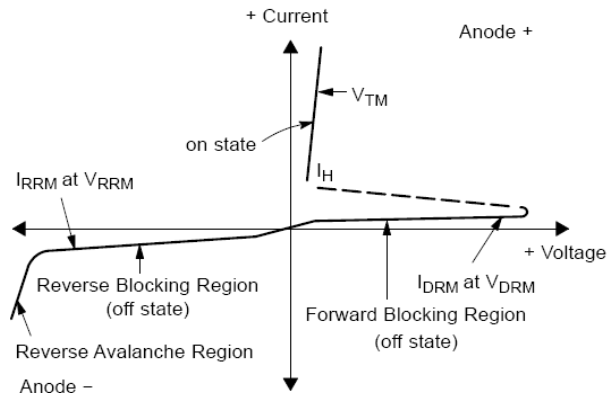
Case	TO-220AB
Marking	Alpha-numeric
Pin out	See below



	TO-220AB			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.575	0.620	14.600	15.750
B	0.380	0.405	9.650	10.290
C	0.160	0.190	4.060	4.820
D	0.025	0.035	0.640	0.890
F	0.142	0.147	3.610	3.730
G	0.095	0.105	2.410	2.670
H	0.110	0.155	2.790	3.930
J	0.014	0.022	0.360	0.560
K	0.500	0.562	12.700	14.270
L	0.045	0.055	1.140	1.390
N	0.190	0.210	4.830	5.330
Q	0.100	0.120	2.540	3.040
R	0.080	0.110	2.040	2.790
S	0.045	0.055	1.140	1.390
T	0.235	0.255	5.970	6.480
U	-	0.050	-	1.270
V	0.045	-	1.140	-
Z	-	0.080	-	2.030

Voltage Current Characteristic of SCR

Symbol	Parameter
V_{DRM}	Peak Repetitive Off State Forward Voltage
I_{DRM}	Peak Forward Blocking Current
V_{RRM}	Peak Repetitive Off State Reverse Voltage
I_{RRM}	Peak Reverse Blocking Current
V_{TM}	Peak On State Voltage
I_H	Holding Current



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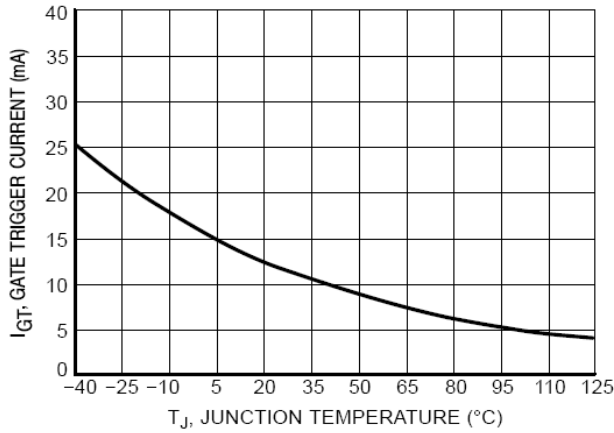


Figure 1. Typical Gate Trigger Current versus Junction Temperature

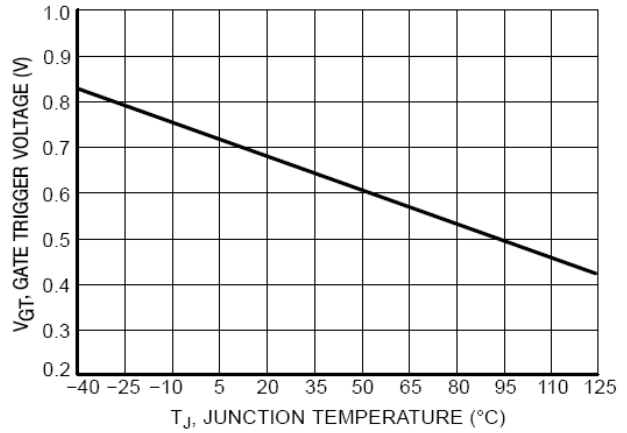


Figure 2. Typical Gate Trigger Voltage versus Junction Temperature

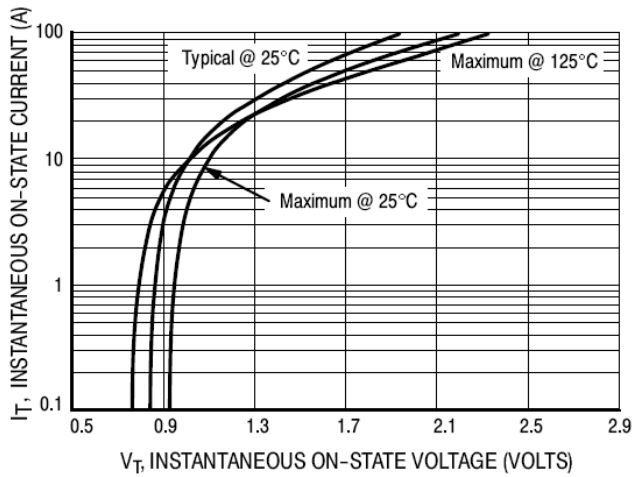


Figure 3. Typical On-State Characteristics

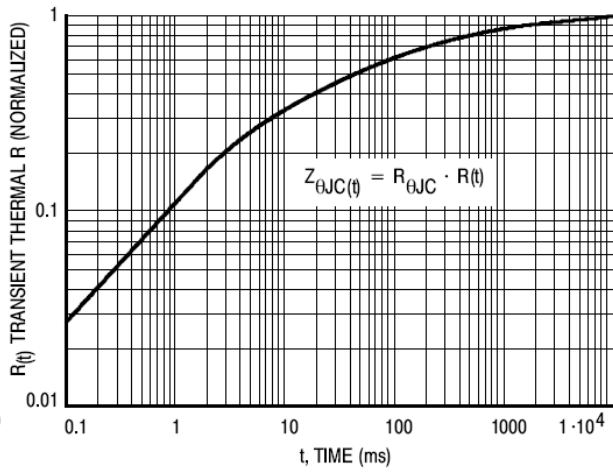


Figure 4. Transient Thermal Response

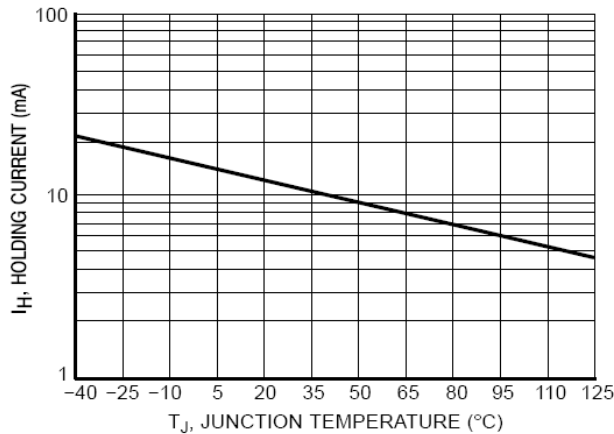


Figure 5. Typical Holding Current versus Junction Temperature

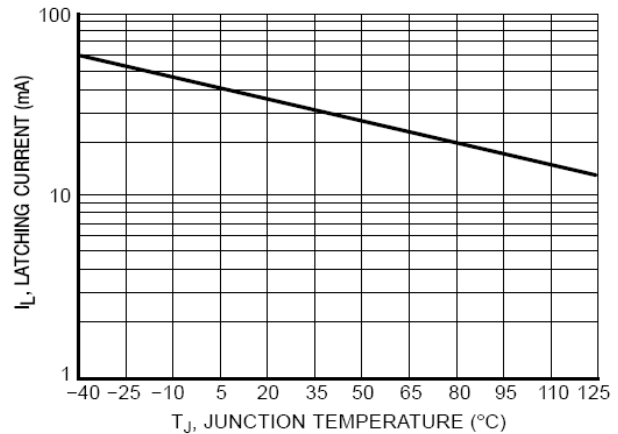


Figure 6. Typical Latching Current versus Junction Temperature

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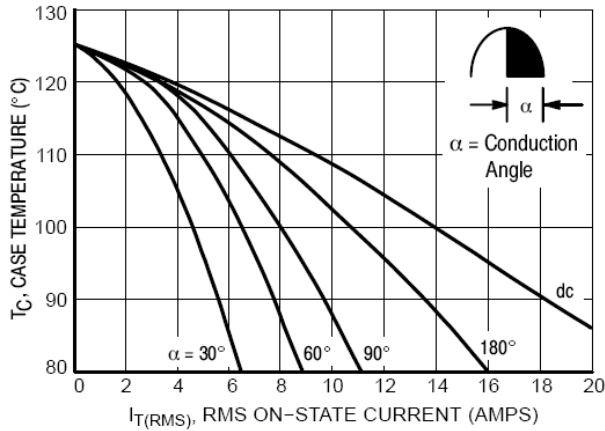


Figure 7. Typical RMS Current Derating

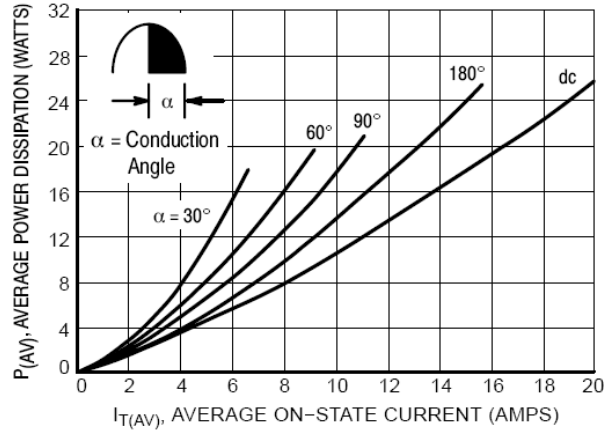


Figure 8. On State Power Dissipation

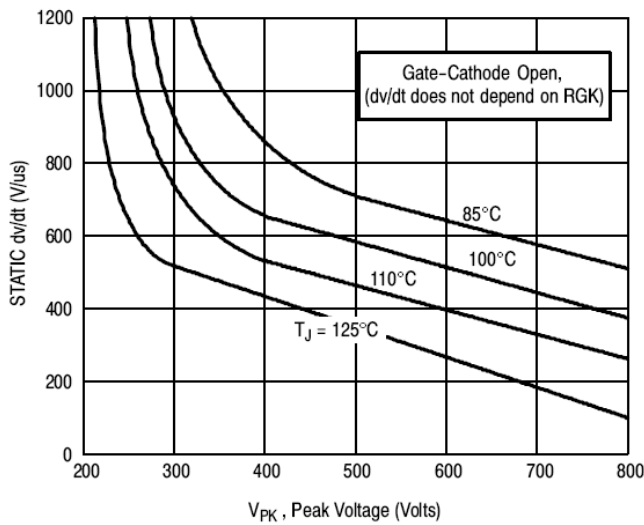


Figure 9. Typical Exponential Static dv/dt Versus Peak Voltage

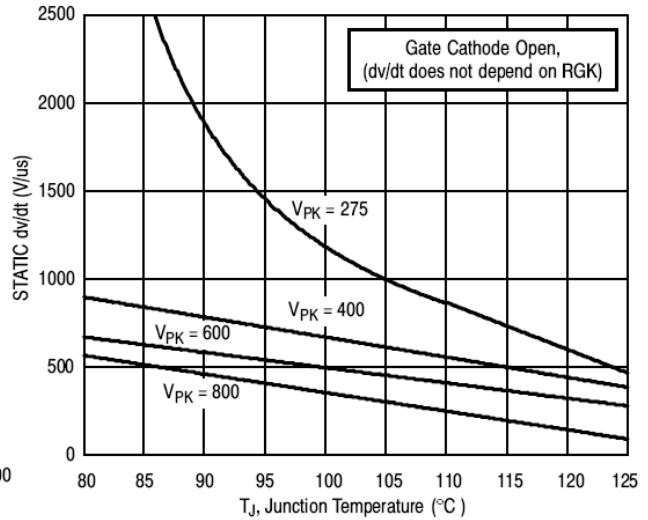


Figure 10. Typical Exponential Static dv/dt Versus Junction Temperature

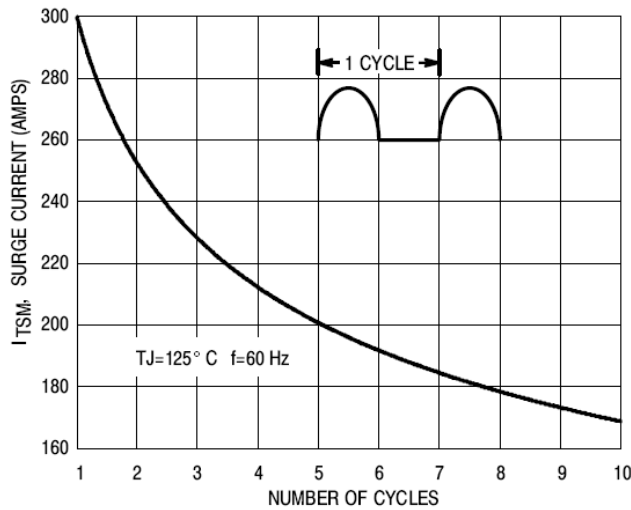


Figure 11. Maximum Non-Repetitive Surge Current